

<b>FORM PTO-1449</b>	Atty. Docket No.: I69.12-0609	Application No.:
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	First Named Inventor: David J. Larson et al.	
	Filing Date: Herewith	Group Art: <i>2652</i>

## U.S. PATENT DOCUMENTS

Examiner Initials	Document No.	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Documents
AA			
AB			
AC			
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AE			
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AG			
AH			
AI			
AJ			
AK			

## FOREIGN PATENT DOCUMENTS

	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Documents	Translation Yes No
AL				
AM				
AN				

EXAMINER: <i>Mm lws</i>	DATE CONSIDERED: <i>12/22/05</i>
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	AU	Jongill Hong, <i>Member, IEEE</i> , and Shan X. Wang, <i>Member, IEEE</i> Microstructures of FeTaN Films in the Neck Region of Magnetic Recording Heads, July 2001, Pages 3039-3042.
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M. C. G. W.

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